

# PECVD(SiNx)

Designed to apply anti-reflective coating to the surface of crystalline silicon wafers to reduce reflection for greater efficiency.

## SOLAR TECHNOLOGY CELL PROCESS MACHINE

### Technical Specification

Format(mm)	1,630(W) x 7,420(L) x 3,500(H)
Weight(kg)	8,400
Gas Supply	SiH <sub>4</sub> , NH <sub>3</sub> , N <sub>2</sub> O=O
Number of Chamber	4
Cycle Time(min)	32
Uptime(%)	96.9
Boat Capacity	336 wafers/Boat
Wafer Throughput	2,500 wafers with boat wafer 336
Cell Type	Monocrystalline, Multicrystalline Silicon wafers
Cell Size(mm)	M2(156*156) ~ M4(161.7*161.7)
Cell Thickness(um)	120 ~ 200(±20)
Process Temperature(°C)	300 ~ 550
Process Pressure(Torr)	0.5 ~ 3.0

### Dimension

